

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

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Features

- Superior circuit protection
- Overcurrent protection
- Blocks surges up to rated voltage limit
- High-speed performance
- Small SMT package
- RoHS compliant*
- AEC-Q101 compliant**

Applications

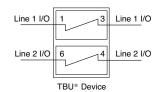
- RS-485 interfaces
- Exposed sense and data lines
- Factory automation
- Automotive battery management systems
- Protection modules and dongles
- Process control equipment
- Test and measurement equipment

TBU-DB-Q Series - TBU® High-Speed Protectors

General Information

The TBU-DB-Q Series of Bourns® TBU® products are low capacitance dual bidirectional high-speed protection components, constructed using MOSFET semiconductor technology, and designed to protect against faults caused by short circuits, overvoltage transients and faults in battery cells, up to rated limits.

The TBU® high-speed protector placed in the system circuit will monitor the current with the MOSFET detection circuit triggering to provide an effective barrier behind which sensitive electronics will not be exposed to large currents during transient events.



The TBU® device is provided in a surface mount DFN package and meets industry standard requirements such as RoHS and Pb Free solder reflow profiles.

Absolute Maximum Ratings (@ T_A = 25 °C Unless Otherwise Noted)

Symbol	Parameter	Value	Unit
V _{imp}	Peak impulse voltage withstand with duration less than 10 ms	550	V
V _{dc}	Peak DC voltage withstand with duration less than 1 hour	450	V
T _{op}	Operating temperature range	-55 to +125	°C
T _{stg}	Storage temperature range	-65 to +150	°C
T _{amax}	Maximum Ambient Temperature	+125	°C

Electrical Characteristics (@ T_A = 25 °C Unless Otherwise Noted)

Symbol	Parameter	Min.	Тур.	Max.	Unit
I _{trigger}	Current required for the device to go from operating state to protected state	100	150	200	mA
R _{device}	Series resistance of the TBU® device	10.5	13.5	16.5	Ω
R _{match}	Package resistance matching of the TBU® device #1 - TBU® device #2			±0.5	Ω
t _{block}	Time taken for the device to go into current limiting		1		μs
IQ	Current through the triggered TBU® device with 50 Vdc circuit voltage		0.5		mA
V _{reset}	Voltage below which the triggered TBU® device will transition to normal operating state	4.5	7.5	9.5	V
R _{th(j-a)}	Junction to package pads - FR4 using JESD51-3 board		125		°C/W
R _{th(j-a)}	Junction to package pads - FR4 using JESD51-7 board		50		°C/W

Environmental Characteristics

Parameter	Value
Moisture Sensitivity Level	1
ESD Classification (HBM)	1B

^{*} RoHS Directive 2002/95/EC Jan. 27, 2003 including annex and RoHS Recast 2011/65/EU June 8, 2011.

Specifications are subject to change without notice.

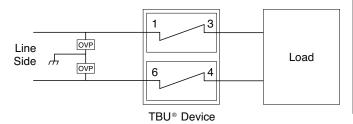
Users should verify actual device performance in their specific applications.

^{**&}quot;Q" part number suffix for automotive and other applications requiring appropriate AEC-Q101 compliance.

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Reference Application

The TBU® devices are general use protectors used in a wide variety of applications, including telecommunications, industrial communications and automotive battery management systems. The maximum voltage rating of the TBU® device should never be exceeded. Where necessary, an OVP device should be employed to limit the maximum voltage. A cost-effective protection solution combines Bourns® TBU® protection devices with a pair of Bourns® TISP® Overvoltage Protectors or MOVs. For bandwidth sensitive applications, a Bourns® GDT may be substituted for the MOV.



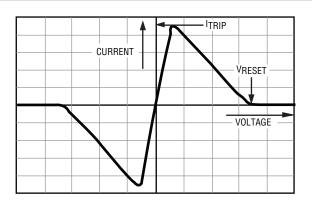
Basic TBU Operation

The TBU® device, constructed using MOSFET semiconductor technology, placed in the system circuit will monitor the current with the MOSFET detection circuit triggering to provide an effective barrier behind which sensitive electronics are not exposed to large voltages or currents during transient events. When operated, the TBU® device will limit the current to less than the l_{trigger} value within the t_{block} duration. If voltage above V_{reset} is continuously sustained, the TBU® device will subsequently reduce the current to a quiescent current level within a period of time that is dependent upon the applied voltage.

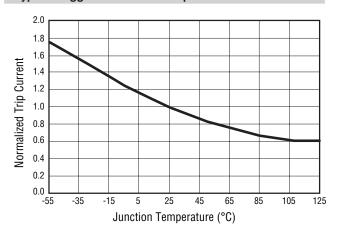
After the surge, the TBU® device resets when the voltage across the TBU® device falls to the V_{reset} level. The TBU® device will automatically reset on lines which have no DC bias or have DC bias below V_{reset} (such as unpowered signal lines).

Performance Graphs

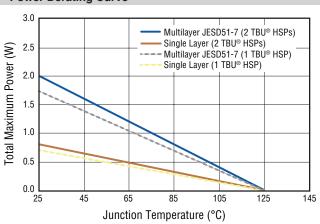
Typical V-I Characteristics



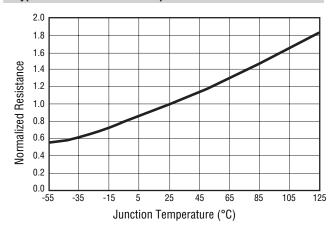
Typical Trigger Current vs. Temperature



Power Derating Curve

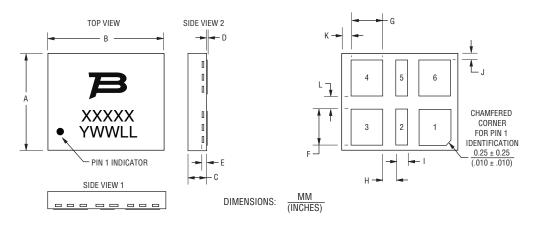


Typical Resistance vs. Temperature



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Product Dimensions



Dim.	Min.	Nom.	Max.				
Α	<u>5.40</u>	<u>5.50</u>	<u>5.60</u>				
	(.213)	(.217)	(.220)				
В	6.40	6.50	6.60				
	(.252)	(.256)	(.260)				
С	<u>0.80</u>	<u>0.90</u>	1.00				
	(.031)	(.035)	(.039)				
D	<u>0.00</u> (.000)		0.05 (.002)				
E		0.20 (.008) REF.					
F	1.90	<u>2.00</u>	<u>2.10</u>				
	(.075)	(.079)	(.083)				
G	1.75	1.85	1.95				
	(.069)	(.073)	(.077)				
Н	<u>0.65</u>	<u>0.70</u>	<u>0.75</u>				
	(.026)	(.028)	(.030)				
I	<u>0.70</u>	<u>0.80</u>	0.90				
	(.028)	(.031)	(.035)				
J	<u>0.30</u>	<u>0.35</u>	<u>0.40</u>				
	(.012)	(.014)	(.016)				
K	<u>0.25</u>	<u>0.30</u>	0.35				
	(.010)	(.012)	(.014)				
L	<u>0.75</u>	<u>0.80</u>	<u>0.85</u>				
	(.030)	(.031)	(.033)				

Pad #	Pin Out				
1	Line 1 In/Out				
2	NU (Not Used)				
3	Line 1 In/Out				
4	Line 2 In/Out				
5	NU (Not Used)				
6	Line 2 In/Out				

NOTES:

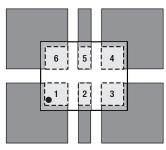
- Pin 1 Indicator is laser marked; radius and location within the Pin 1 terminal.
 - Pin 1 dot size: 0.500 ± 0.125 mm / $.020 \pm .005$ in.
- Pin 2 and 5 are NU (Not Used) and must be left unconnected; do not connect to In/Out lines, do not connect to system Ground.
- 3. Coplanarity on exposed pads shall not exceed 0.08 mm / .003 in.
- 4. Warpage shall not exceed 0.10 mm / .004 in. on all surfaces.
- 5. Exposed tie bars at package side are not plated.

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Recommended Pad Layout

TBU® High-Speed Protectors have a 100 % matte-tin termination finish. For improved thermal dissipation, the recommended layout uses PCB copper areas which extend beyond the exposed solder pad. The exposed solder pads should be defined by a solder mask which matches the pad layout of the TBU® device in size and spacing. It is recommended that they should be the same dimension as the TBU® pads but if smaller solder pads are used, they should be centered on the TBU® package terminal pads and not more than 0.10-0.12 mm (0.004-0.005 in.) smaller in overall width or length. Solder pad areas should not be larger than the TBU® pad sizes to ensure adequate clearance is maintained. The recommended stencil thickness is 0.10-0.12 mm (0.004-0.005 in.) with a stencil opening size 0.025 mm (0.0010 in.) less than the solder pad size. Extended copper areas beyond the solder pad significantly improve the junction to ambient thermal resistance, resulting in operation at lower junction temperatures with a corresponding benefit of reliability. All pads should soldered to the PCB, including pads marked as NC or NU but no electrical connection should be made to these

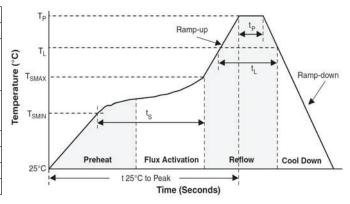
pads. Care should be taken to assure no resistive path exists between the NU pins to any other point to avoid unexpected performance issues. For minimum parasitic capacitance, it is recommended that signal, ground or power signals are not routed beneath any pad.

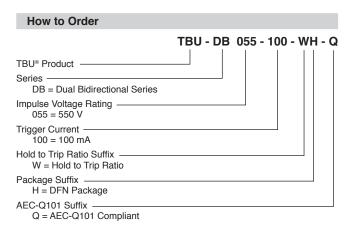


Dark grey areas show added PCB copper area for better thermal resistance.

Reflow Profile

Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate (Tsmax to Tp)	3 °C/sec. max.
Preheat - Temperature Min. (Tsmin) - Temperature Max. (Tsmax) - Time (tsmin to tsmax)	150 °C 200 °C 60-180 sec.
Time maintained above: - Temperature (TL) - Time (tL)	217 °C 60-150 sec.
Peak/Classification Temperature (Tp)	260 °C
Time within 5 °C of Actual Peak Temp. (tp)	20-40 sec.
Ramp-Down Rate	6 °C/sec. max.
Time 25 °C to Peak Temperature	8 min. max.





MANUFACTURER'S
TRADEMARK

5 DIGIT PRODUCT CODE:

15T ALPHA CHARACTER INDICATES PRODUCT FAMILY:

8 = TBU-DB SERIES:

2 ND & 3 RD DIGITS INDICATE IMPULSE VOLTAGE.

4 TH & 5 TH DIGITS INDICATE TRIGGER CURRENT.

UNDERSCORE DENOTES AEC-Q101 COMPLIANCE.

PIN 1 INDICATOR

MANUFACTURING
DATE CODE:

1 ST DIGIT INDICATES THE YEAR.

2 ND & 3RD DIGITS INDICATE THE WEEK NUMBER.

4 TH & 5 TH DIGITS INDICATE LOT CODE.

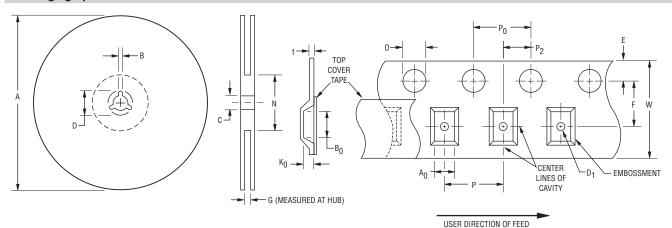
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Packaging Specifications



QUANTITY: 3000 PIECES PER REEL

Α		E	3	С		D		G	N
Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Ref.	Ref.
328.5 (12.93)	331 (13.05)	2.0 (0.079)	(0.094)	12.8 (0.504)	<u>13.5</u> (.531)	17.0 (0.669)	<u>17.4</u> (0.690)	16.5 (0.650)	$\frac{100 \pm 1.5}{(3.94 \pm 0.059)}$

A ₀		В0		D ₀		D ₁		E		F	
Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	max.
5.75	5.95	6.75	6.95	1.5	1.6	1.5	_	1.65	1.85	7.4	7.6
(0.224)	(0.234)	(0.266)	(0.274)	(0.059)	(0.063)	(0.059)		(0.065)	(0.073)	(0.291)	(0.299)
K ₀		F	P		P ₀		P ₂		t	W	
Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.
1.05	1.25	7.9	8.1	3.9	4.1	1.9	2.1	0.25	0.35	15.7	16.3
(0.041)	(0.049)	$(\overline{0.311})$	$(\overline{0.319})$	$(\overline{0.159})$	(0.161)	(0.075)	(0.083)	(0.010)	$(\overline{0.014})$	$(\overline{0.618})$	(0.642)

DIMENSIONS: $\frac{MM}{(INCHES)}$

BOURNS®

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